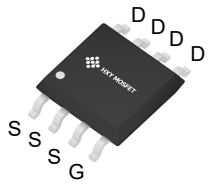
SQ4425EY-T1_BE3

P-Channel Enhancement Mode MOSFET

Description

The SQ4425EY-T1_BE3 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V.This device is suitable for use as a Battery protection or in other Switching application.

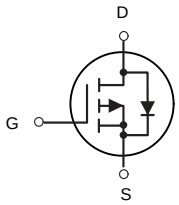


SOP-8

General Features

V_{DS} = -30V I_D = -12A

$R_{DS(ON)}$ < 15mΩ@ V_{GS}=10V



P-Channel MOSFET

Application

Battery protection

Load switch

Uninterruptible power supply

Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SQ4425EY-T1_BE3	SOP-8	HXY MOSFET	3000

Absolute Maximum Ratings(Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_A=25°C	Drain Current , V_{GS} @ 10V	-12	A
I_D@T_A=70°C	Drain Current , V_{GS} @ 10V	-9.1	A
I_{DM}	Pulsed Drain Current	-40	A
P_D@T_A=25°C	Total Power Dissipation	2.5	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
Rthj-a	Maximum Thermal Resistance, Junction-ambient	50	°C/W

Electrical Characteristics@T_j=25 °C(unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D= -250μA	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}= -30V, V_{GS}=0V,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	V_{DS}=0V, V_{GS}= ±20V	-	-	±100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D= -250μA	-1.0	-1.6	-2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance Note3	V_{GS}= -10V, I_D= -10A	-	10	15	mΩ
		V_{GS}= -4.5V, I_D= -5A	-	17	24	
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS}= -15V, V_{GS}=0V, f=1.0MHz	-	1770	-	pF
C_{oss}	Output Capacitance		-	233	-	pF
C_{rss}	Reverse Transfer Capacitance		-	206	-	pF
Q_g	Total Gate Charge	V_{DS}= -15V, I_D= -5A, V_{GS}= -10V	-	22	-	nC
Q_{gs}	Gate-Source Charge		-	1.0	-	nC
Q_{gd}	Gate-Drain(“Miller”) Charge		-	1.8	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	V_{DD}= -15V, I_D= -10A, V_{GS}=-10V, R_{GEN}=2.5Ω	-	9	-	ns
t_r	Turn-on Rise Time		-	13	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	48	-	ns
t_f	Turn-off Fall Time		-	20	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-12	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-60	A
V_{SD}	Drain to Source Diode Forward Voltage	V_{GS}=0V, I_S= -15A	-	-0.8	-1.2	V
trr	Reverse Recovery Time	T_J=25℃, V_{DD}= -24V,I_F=-2.8A, dI/dt=-100A/μs	-	64	-	ns
Qrr	Reverse Recovery Charge		-	25	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: T_J=25℃, V_{GS}=10V, R_G=25Ω, L=0.5mH, I_{AS}=-12.7A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Characteristics

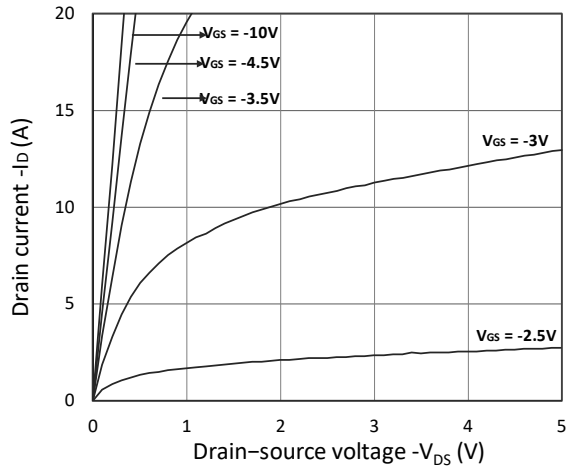


Figure 1. Output Characteristics

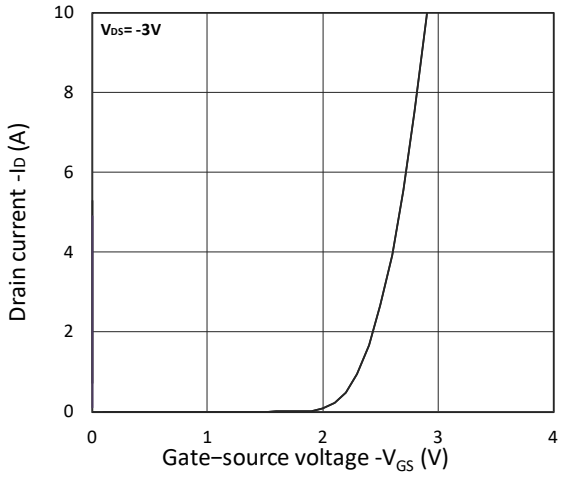


Figure 2. Transfer Characteristics

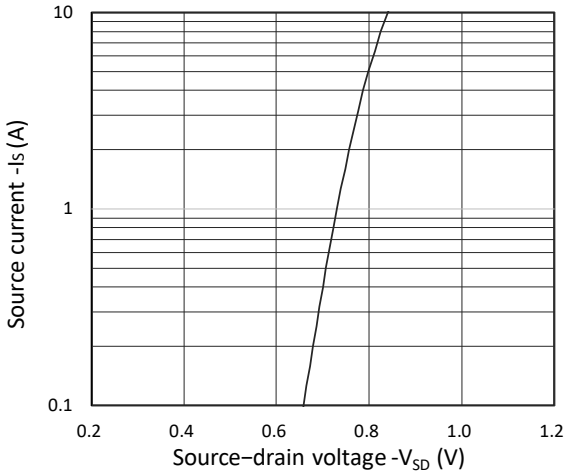


Figure 3. Forward Characteristics of Reverse

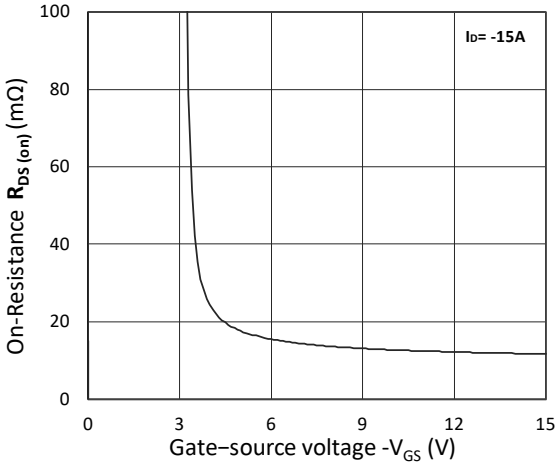


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

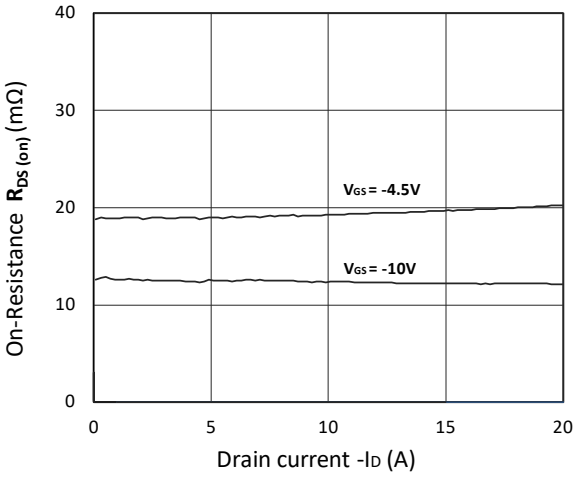


Figure 5. $R_{DS(ON)}$ vs. I_D

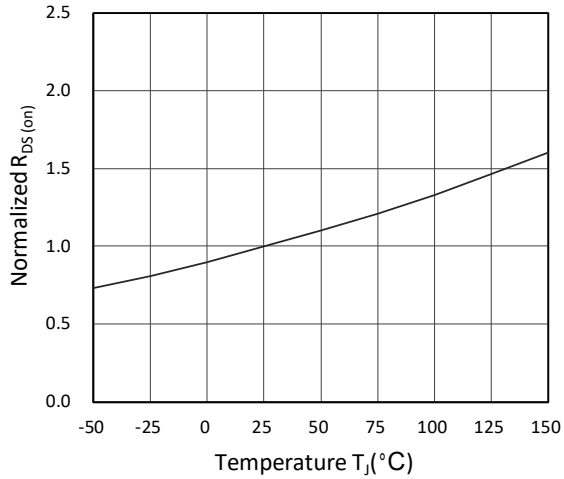


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

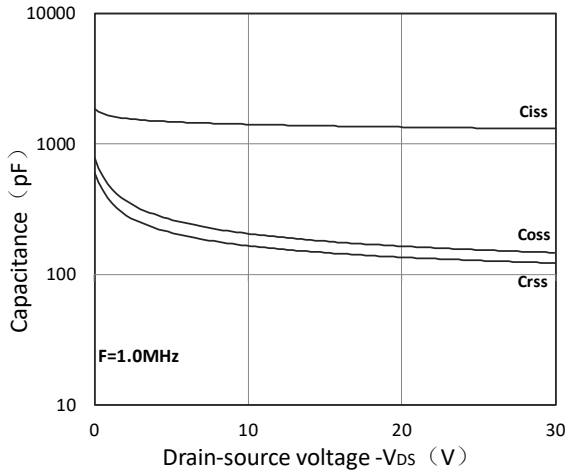


Figure 7. Capacitance Characteristics

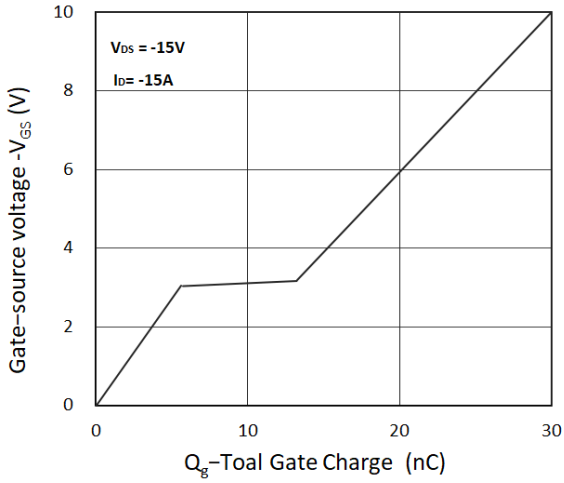


Figure 8. Gate Charge Characteristics

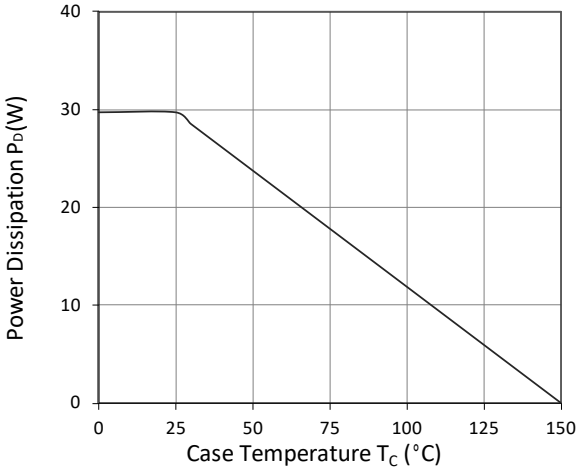


Figure 9. Power Dissipation

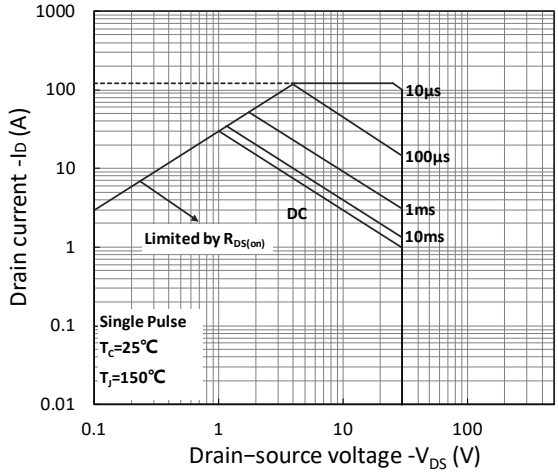


Figure10. Safe Operating Area

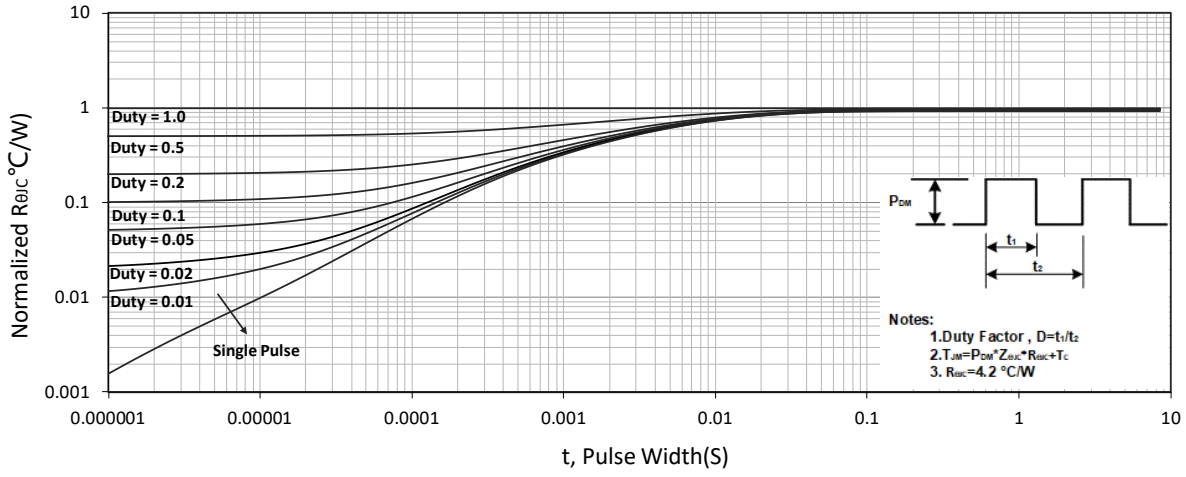
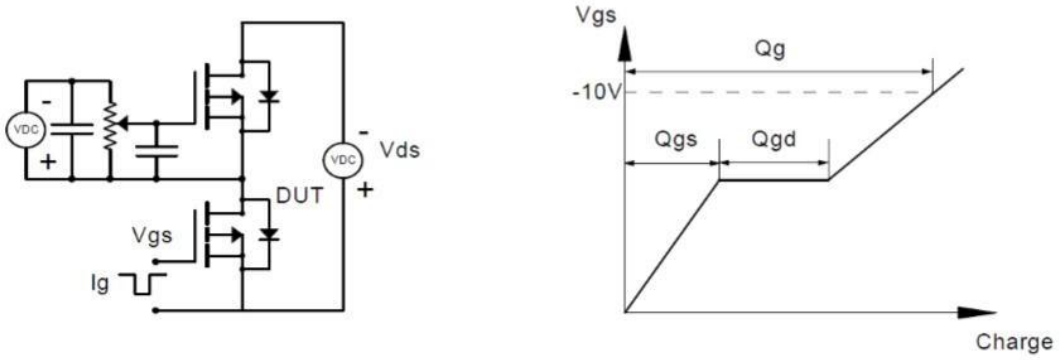


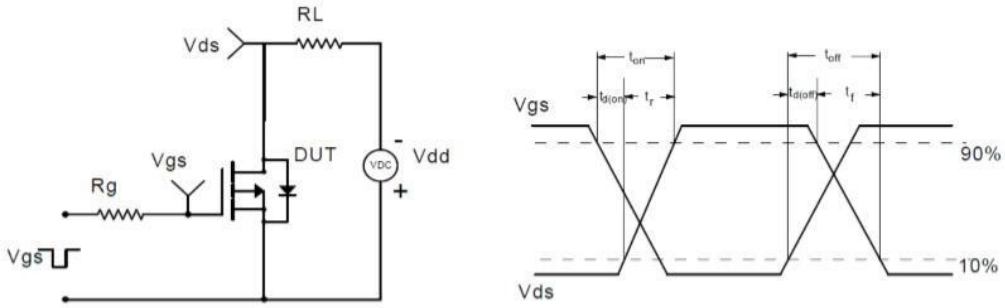
Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

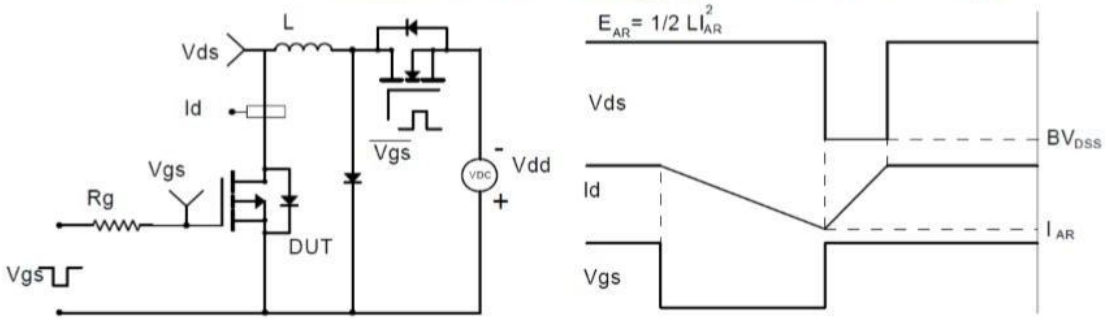
Gate Charge Test Circuit & Waveform



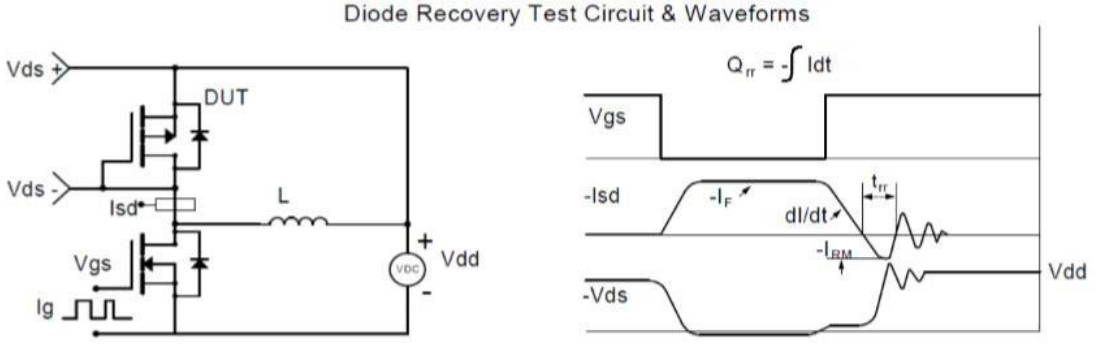
Resistive Switching Test Circuit & Waveforms



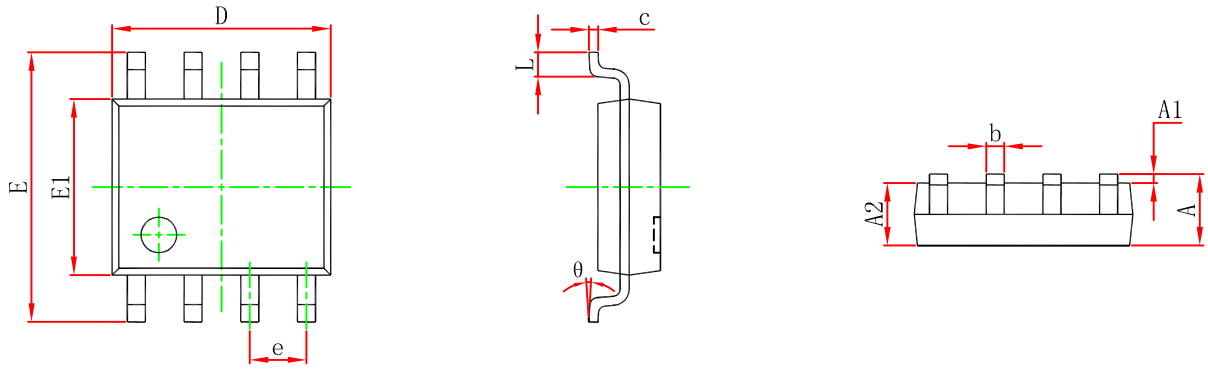
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



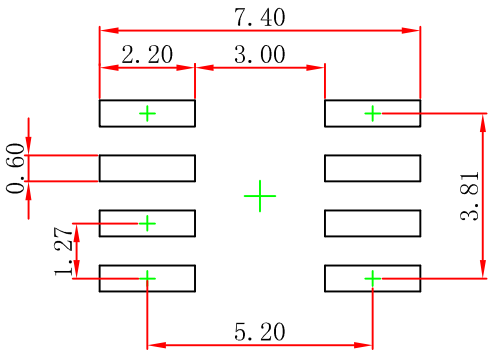
Diode Recovery Test Circuit & Waveforms



SOP-8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	**Max**	**Min**	**Max**
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270（BSC）		0.050（BSC）	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

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